

# **Bill of Materials**

Item	Part	Quantity	Value	Part name	Manufacturer	Description	Package Name	Standard Dimensions mm (inch)	Comment
1	PIR1	1	-	IRA-S410ST01	Murata Manufacturing	Pyroelectric infrared Sensor		Ф9.2×4.7	
2	U1, U2	2	-	TC75S67TU	TOSHIBA	Operational amplifier	SOT-353F	2.0×2.1×0.7	
3	C1, C6	2	68 nF			Ceramic 10 V, ±10 %		1.0×0.5 (0402)	
4	C2	1	22 μF			Ceramic 6.3 V, ±10 %		2.0×1.2 (0805)	
5	C3, C5, C11	3	100 nF			Ceramic 16 V, ±10 %		1.0×0.5 (0402)	
6	C4, C10	2	10 nF			Ceramic 25 V, ±10 %		1.0×0.5 (0402)	
7	C7, C12	2	10 µF			Ceramic 25 V, ±10 %		2.0×1.2 (0805)	
8	C8	1	100 μF			Ceramic 6.3 V, ±10 %		3.2×1.6 (1206)	
9	C9	1	1 nF			Ceramic 50 V, ±5 %		1.0×0.5 (0402)	
10	C13	1	470 μF			Tantalum 6.3 V, ±20 %		7.3×4.3 (2917)	
11	R1, R6	2	100 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
12	R2	1						1.0×0.5 (0402)	Not mounted Dummy load
13	R3	1	10 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
14	R4, R7, R8, R11	4	1 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
15	R5	1	4.7 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
16	R9	1	0 Ω			1 A		1.0×0.5 (0402)	
17	R10	1	47 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
18	CN2	1	-	110990030	Seeed Studio	Grove connector 4-pin/straight		10×5.1×8.1	



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